

G363-SR0-AAX4

HPC/AI Server - 3U DP NVIDIA HGX™ H200 4-GPU



Features

- NVIDIA HGX™ H200 4-GPU
- 4th-generation NVIDIA® NVLink® 900GB/s
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Broadcom® BCM57416
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen4 x4 interface
- 6 x LP PCIe Gen5 x16 slots
- 2+1 3000W 80 PLUS Titanium redundant power supplies

Application

AI, AI Inference, AI Training, High-Performance Computing

Specification

Dimensions 3U (W448 x H130 x D800 mm)

Motherboard MS63-HD2

CPU 5th/4th Gen Intel® Xeon® Scalable Processors
Intel® Xeon® CPU Max Series
Dual processor, LGA 4677 (Socket E)
TDP up to 350W

Chipset Intel® C741

Memory 8-Channel DDR5 RDIMM, 16 x DIMMs
5th Gen Intel Xeon: Up to 5600 MT/s
4th Gen Intel Xeon & Intel Xeon Max Series: Up to 4800 MT/s

LAN Front: 2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Support NCSI function
1 x 10/100/1000 management LAN
Rear: 2 x 10Gb/s LAN (1 x Broadcom® BCM57416)

Video Integrated in ASPEED® AST2600 - 1 x VGA port

Storage Front hot-swap:
8 x 2.5" Gen5 NVMe/SATA/SAS-4
*SAS card is required to support SAS drives.
Internal M.2:
1 x M.2 (2280/22110), PCIe Gen4 x4

RAID Intel® SATA RAID 0/1/10/5
Support optional RAID add-in cards

Modular GPU NVIDIA HGX™ H200 with 4 x SXM GPUs

Expansion Slots Front: 2 x LP PCIe Gen5 x16 slots
Rear: 4 x LP PCIe Gen5 x16 slots (with PCIe switches, support RDMA)

I/O ports Front: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN (default)
Rear: 2 x RJ45

TPM 1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)

Backplane Board Speed and bandwidth:
PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s

Power Supply 2+1 3000W 80 PLUS Titanium redundant power supplies
AC Input: 115-240V
*The system power supply requires C19 power cord.

System Management ASPEED® AST2600 Baseboard Management Controller
GIGABYTE Management Console web interface

OS Support Windows Server, Red Hat Enterprise Linux server, Ubuntu,
SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor

System Fans 7 x 80x80x80mm (17,000rpm)

Operating Properties Operating temperature: 10°C to 35°C
Operating humidity: 8-80% (non-condensing)
Non-operating temperature: -40°C to 60°C
Non-operating humidity: 20%-95% (non-condensing)

Packaging Content 1 x G363-SR0-AAX4, 2 x CPU heatsinks, 6 x Carriers,
1 x Mini-DP to D-Sub cable, 1 x L-shape Rail kit
Packaging Dimensions: 1176 x 782 x 295 mm

Part Numbers Barebone w/ NVIDIA module: 6NG363SR0DR000ABX4*
Optional parts:
- C19 power cord 125V/15A (US): 25CP1-018000-Q0R
- C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R
- C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R
- RMA packaging: 6NG363SR0SR-RMA-A100



Learn more at <https://www.GIGABYTE.com/enterprise>

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